

# PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
Name	Execution Date
Tomoo Takada	09/08/2004
Kenichi Kawase	09/09/2004
Isamu Konishiike	09/09/2004
Yukiko Iijima	09/10/2004
Yukio Miyaki	09/15/2004
<b>RECEIVING PARTY DATA</b>	
Name:	Sony Corporation
Street Address:	7-35 Kitashinagawa 6-Chome
Internal Address:	Shinagawa-Ku
City:	Tokyo
State/Country:	JAPAN
<b>PROPERTY NUMBERS Total: 1</b>	
Property Type	Number
Application Number:	10884734
<b>CORRESPONDENCE DATA</b>	
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NAME OF SUBMITTER:	Robert J. Depke
Total Attachments: 2	

CH \$40.00 10884734

**500007696**

**PATENT**  
**REEL: 015165 FRAME: 0186**



## ASSIGNMENT

WHEREAS, I, as a below named inventor, residing at the address stated next to my name, am a sole inventor (if only one name is listed below) or a joint inventor (if plural names are listed below) of certain new and useful improvements in

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**ANODE AND BATTERY USING IT**

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for which an application for Letters Patent of the United States of America was executed by me on the date indicated next to my name and address;

AND WHEREAS, Sony Corporation, a Japanese corporation with offices at 7-35 Kitashinagawa 6-Chome, Shinagawa-Ku, Tokyo, Japan (hereinafter referenced as ASSIGNEE) is desirous of acquiring all interest in, to and under said invention, said application disclosing the invention and in, to and under any Letters Patent or similar legal protection which may be granted therefor in the United States and in any and all foreign countries;

NOW THEREFORE, in consideration of the sum of One Dollar (\$1.00), and other good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, I, as a sole or joint inventor as indicated below, do hereby assign, sell and transfer unto the said ASSIGNEE, its successors, assigns, the entire right, title and interest in the said invention, said application, including any divisions and continuations as well as any reissues and reexaminations thereof, and in and to any and all Letters Patent of the United States, and countries foreign thereto, which may be granted for said invention, and in and to any and all priority rights and/or convention rights under the International Convention for the Protection of Industrial Property, Inter-American Convention Relating to Patents, Designs and Industrial Models, and any other international agreements to which the United States of America adheres, and to any other benefits accruing or to accrue to me with respect to the filing of applications for patents or securing of patents in the United States and countries foreign thereto, and I hereby authorize and request the Commissioner of Patents to issue the said United States Letters Patent to said ASSIGNEE, as the assignee of the whole right, title and interest thereto;

And I further agree to execute all necessary or desirable and lawful future documents, including assignments in favor of ASSIGNEE or its designee, as ASSIGNEE or its successors, assigns may from time-to-time present to me and without further remuneration, in order to perfect title in said invention, modifications, and improvements in said invention, applications and Letters Patent of the United States and countries foreign thereto;

And I further agree to properly execute and deliver and without further remuneration, such necessary or desirable and lawful papers for application for foreign patents, for filing subdivisions of said application for patent, and or, for obtaining any reissue or reissues of any Letters Patent which may be granted for my aforesaid invention, as the ASSIGNEE thereof shall hereafter require and prepare at its own expense;

And I further agree that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said application, said invention and said Letters Patent and legal equivalents in foreign countries as may be known and accessible to me and will testify as to the same in any interference or litigation related thereto;

And I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale.

And I hereby authorize and request my attorney(s) of record in this application to insert the serial number and filing date of this application in the spaces that follow: Serial No. 10/884,734 Filing Date: July 2, 2004

This assignment executed on the dates indicated below.

Tomoo TAKADA

Name of first or sole inventor

Execution date of U.S. Patent Application

Fukushima, Japan

Residence of first or sole inventor

*Tomoo Takada*

*September 8, 2004*

Signature of First or sole inventor

Date of this Assignment

Kenichi KAWASE

Name of second inventor

Fukushima, Japan

Residence of second inventor

Execution date of U.S. Patent Application

*Kenichi Kawase*

Signature of second inventor

*September 9, 2004*

Date of this Assignment

Isamu KONISHIIE

Name of third inventor

Fukushima, Japan

Residence of third inventor

Execution date of U.S. Patent Application

*Isamu Konishiie*

Signature of third inventor

*September 9, 2004*

Yukiko IJIMA

Name of fourth inventor

Date of this Assignment

Fukushima, Japan

Residence of fourth inventor

Execution date of U.S. Patent Application

*Yukiko Iijima*

Signature of fourth inventor

*September 10, 2004*

Date of this Assignment

Yukio MIYAKI

Name of fifth inventor

Execution date of U.S. Patent Application

Kanagawa, Japan

Residence of fifth inventor

*Yukio Miyaki*

Signature of fifth inventor

*September 15, 2004*

Date of this Assignment

Name of sixth inventor

Execution date of U.S. Patent Application

Residence of sixth inventor

Signature of sixth inventor

Date of this Assignment

Name of seventh inventor

Execution date of U.S. Patent Application

Residence of seventh inventor

Signature of seventh inventor

Date of this Assignment